

Benchtop Reflow Oven HR-10

Smart Equipment for Industry 4.0



- · Small batch oven for ROHS lead-free soldering
- Controlled via buttons and LCD display at front panel
- Programmable with Android application from tablet or smartphone
- 7" tablet included in standard oven delivery
- · Android App upgrades available from Google Play
- 99 reflow or dry programs preprogrammed and editable
- 2 models motor driven or manual door opening
- · Automatic forced PCB cooling after reflowing
- Solder fumes exhaust from the reflow chamber optional



Reflow process

Benchtop Reflow oven with IR and convection heating. Forced hot-air convection ensures uniform temperature profile within the whole solder chamber. Fans placed under the grate ensure optimal cooling of PCB for achieving perfect solder joint structure.

How does it work?

Connect the oven to a power source and the dump exhaust to an exhaust unit FE-10. The oven is searching for a paired tablet or smartphone. When one of those devices is connected, start the Android App.

You can set basic app and oven parameters as well as an option to program desired temperature profiles. When the oven is properly programmed, the user can control the process with buttons and LCD display at the front panel. There is an sound signal when the reflow process is over. The same signal appears in the tablet or smartphone. Immediately after soaking is started exhaust and after door opening also fans started forced cooling.

The Android application displays the process status, time and temperature or other info. An application for IOS systems is being planned.







(Screenshots of Android application)

| | Technical details |
|-----------------------------------|--|
| Max. PCB size | 320 x 220 mm |
| Max. preheat temperaure | 200 °C |
| Preheat time | 10 - 600 s |
| Max. reflow temperature | 260 °C |
| Reflow time | 1 - 300 s |
| Preparing time before first cycle | < 5 min |
| Preparing time between cycles | < 3 min |
| Max. drying temperature | 150 °C |
| Drying time | 1 - 999 mins = 16 hours |
| Cooling | 2 fans on the base, 360 l/min |
| Solder fumes exhaust | Switched after reflow, 1500 I/min (Option) |
| Number of programms | 99 - reflow or dry |
| Measuring thermocouples | K-type, 2 pcs insde chamber + 1 external |
| Max. component height | 55 mm to the top, 30 mm to the bottom |
| Power supply / consumption | 230 V, 50 Hz, single-phase, 3100 W max. |
| Operating conditions | Temperature 15 - 30 °C , Humidity 30 - 80 % RH |
| Dimensions (L x W x H) | 505 x 362 x 340 mm |
| Weight | 18 kgs |